



US00D339110S

# United States Patent [19]

Steen, Jr. et al.

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[45] Date of Patent: **\*\* Sep. 7, 1993**

[54] **HEAT SINK CLIP FOR SURFACE-MOUNT INTEGRATED CIRCUIT**

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of Ill.**

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[\*\*] Term: **14 Years**

### [57] CLAIM

[21] Appl. No.: **754,133**

The ornamental design for a heat sink clip for surface-mount integrated circuit, as shown and described.

[22] Filed: **Sep. 3, 1991**

### DESCRIPTION

[52] U.S. Cl. .... **D13/179**

[58] Field of Search ..... **D13/179; 165/80.2;  
257/713, 718; 361/383, 386; 174/16.3**

FIG. 1 is a front, top, and right side perspective view showing our new design for a heat sink clip for surface-mount integrated circuit;

### [56] References Cited

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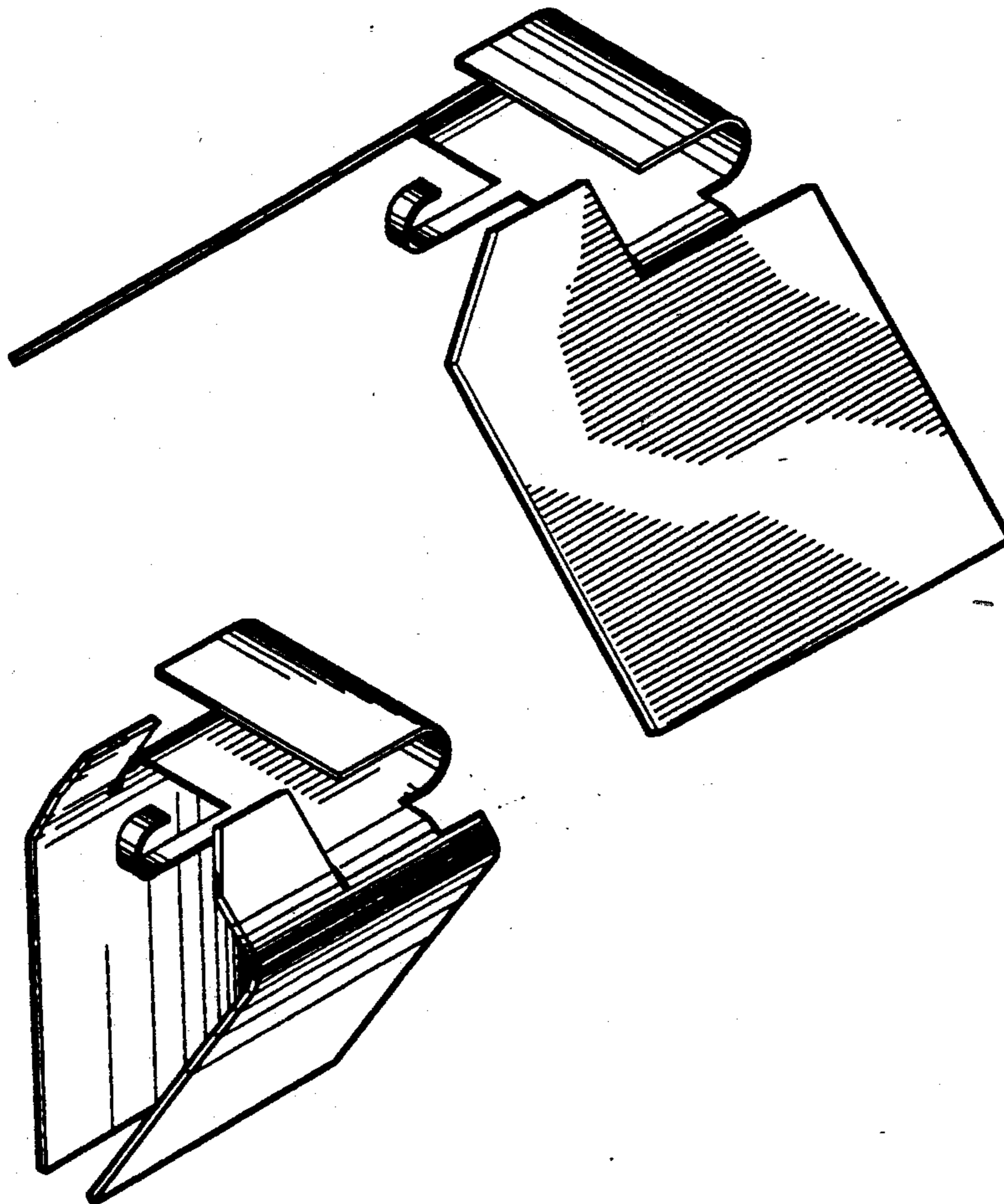
D. 262,203 12/1981 Johnson et al. .... D13/179  
D. 275,749 10/1984 McCarthy ..... D13/179  
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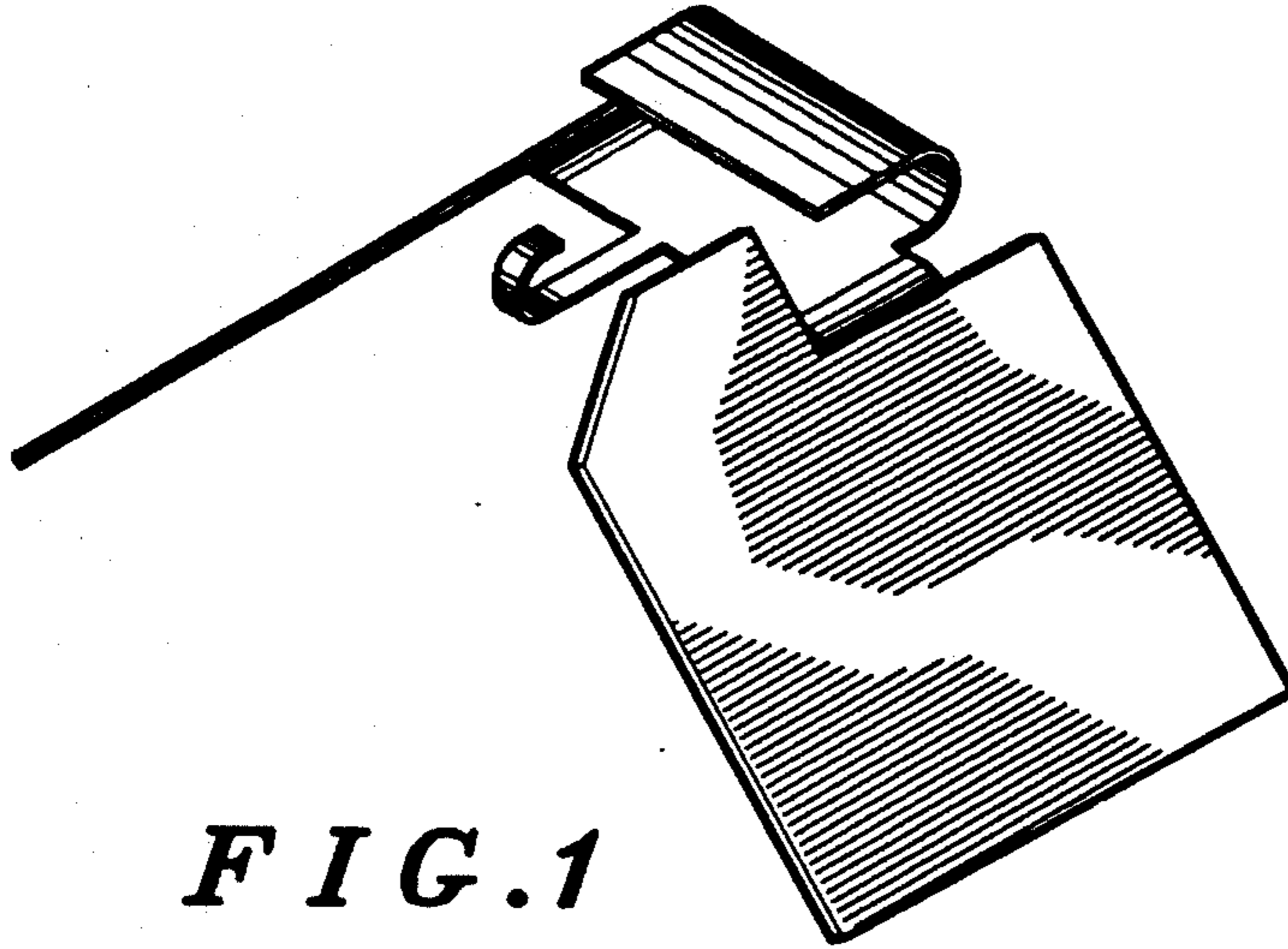
FIG. 2 is a left elevational view thereof;

FIG. 3 is a rear elevational view thereof;

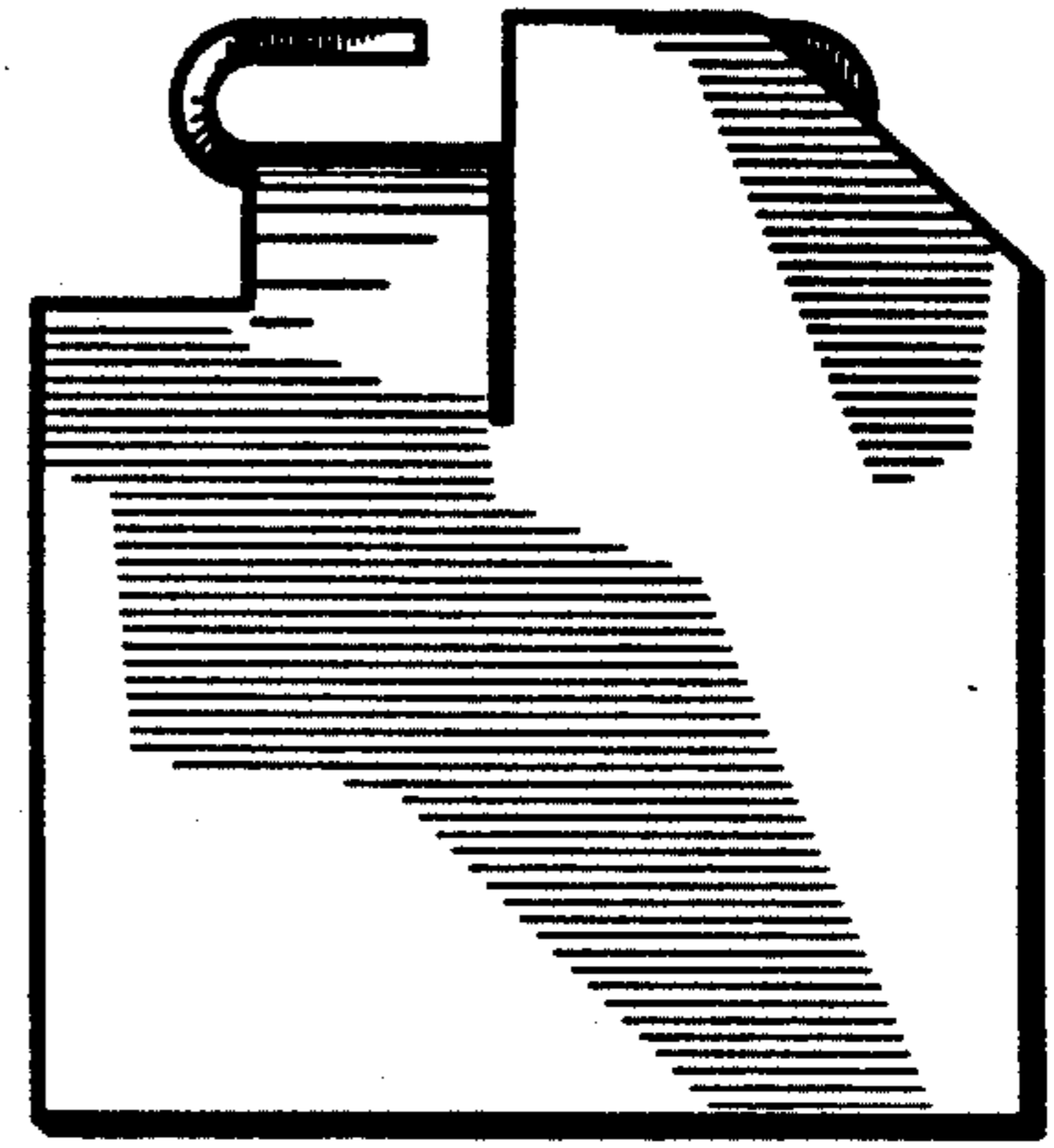
FIG. 4 is a bottom plan view thereof; and,

FIG. 5 is a front, top, and right side perspective view showing an alternate embodiment for a heat sink clip for surface mount integrated circuit, the front, top, and left side perspective view being a mirror image.

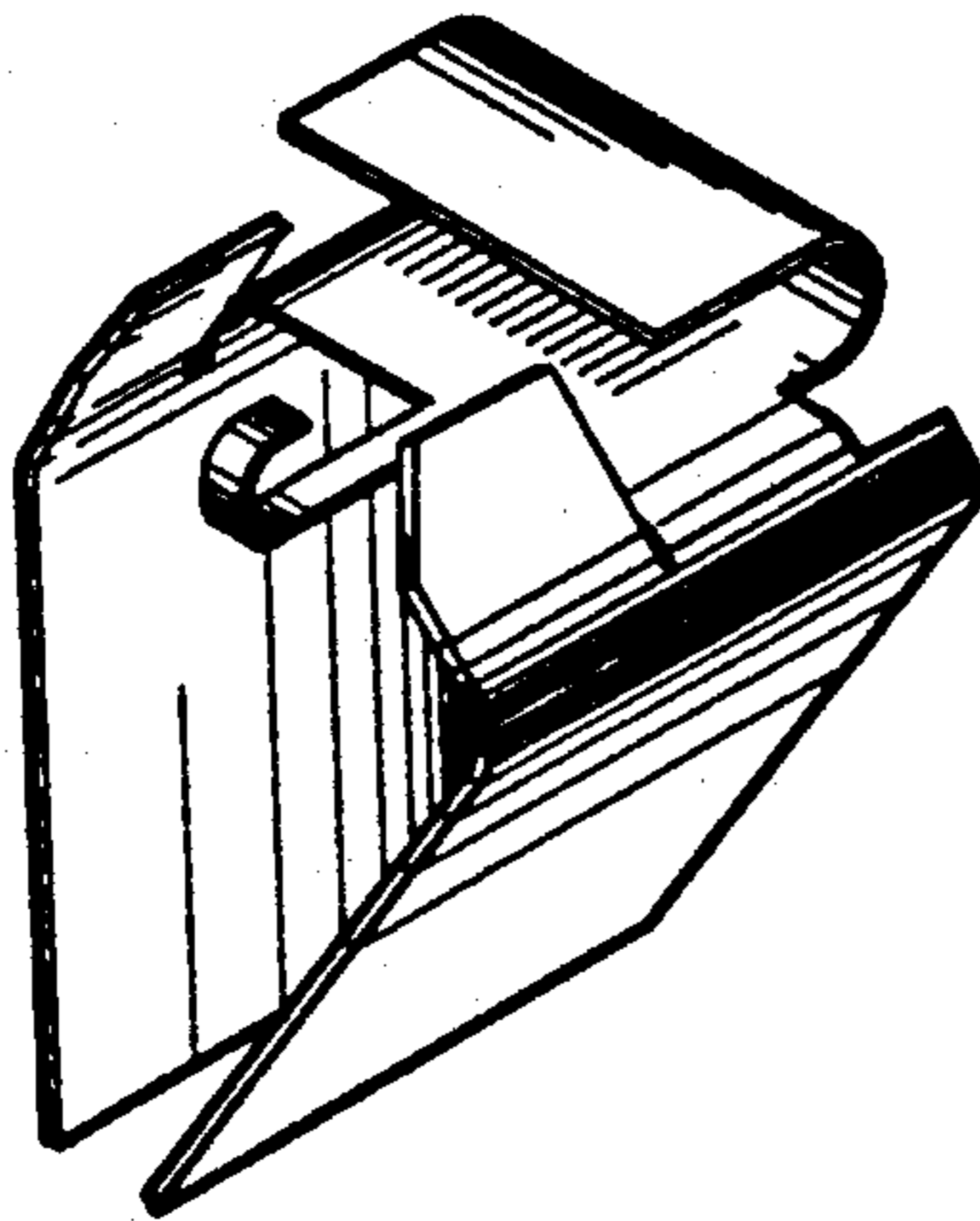




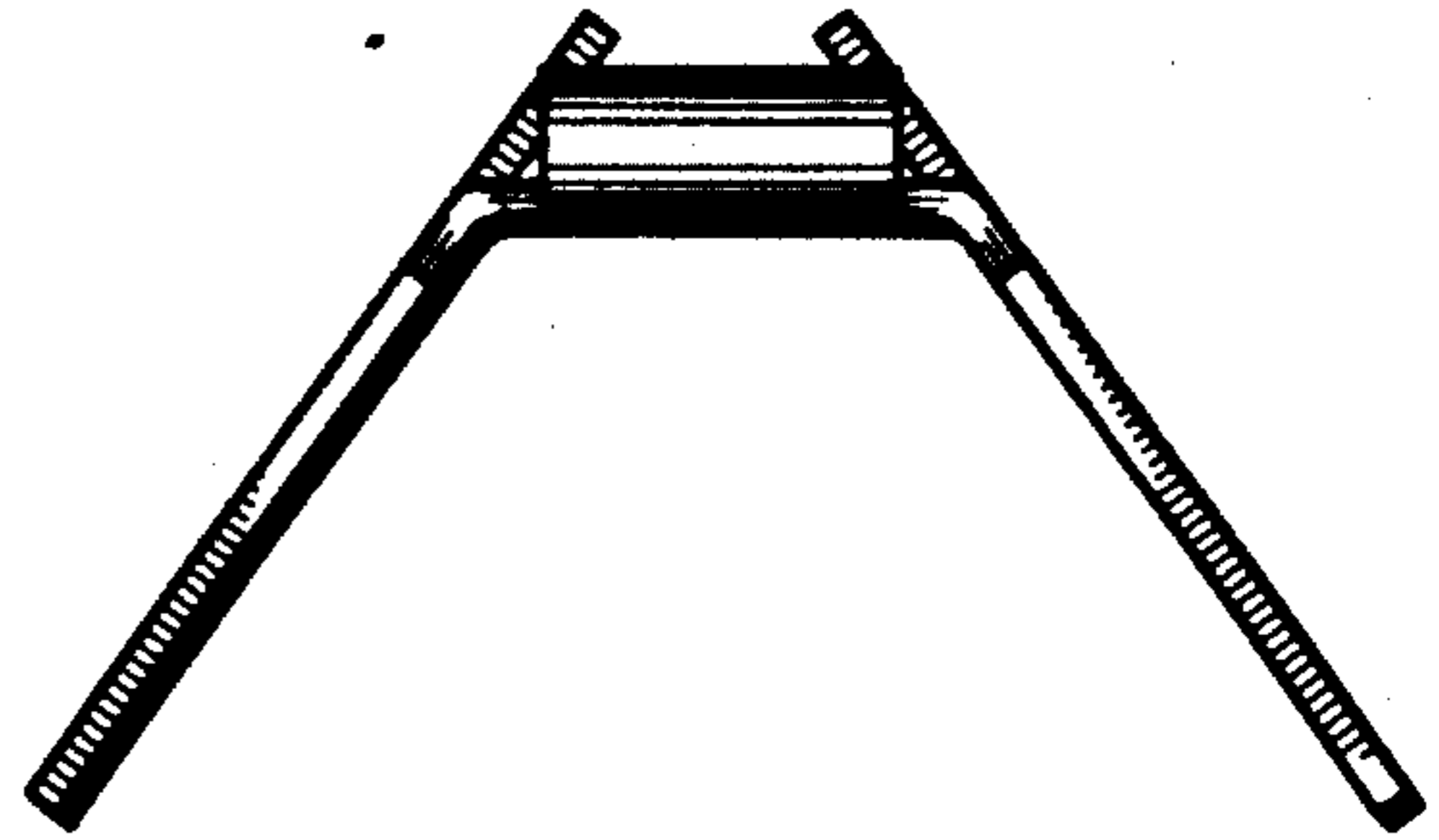
*FIG. 1*



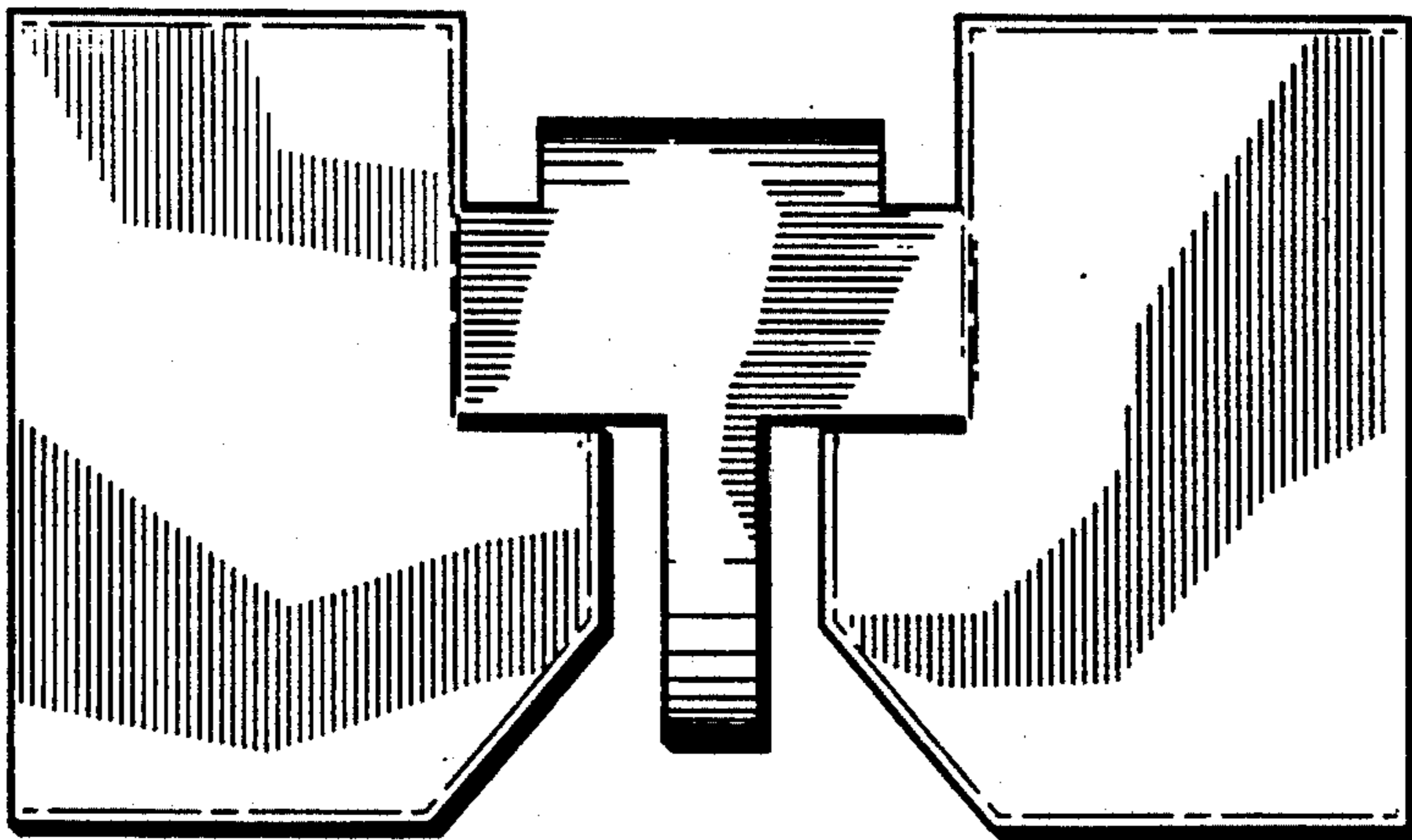
*FIG. 2*



*FIG. 5*



*FIG. 3*



*FIG. 4*